



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20210326003.1

**Transfer of select C10 devices from ANAM-1 to DMOS5 Wafer Fab site
Change Notification / Sample Request**

Date: March 31, 2021

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

PCN Team
SC Business Services

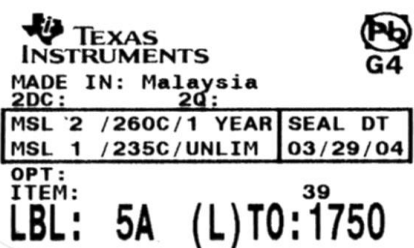

20210326003.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CDCLVD1204RGTR	null
CDCLVD1204RGTT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210326003.1		PCN Date:	Mar 31, 2021																			
Title:	Transfer of select C10 devices from ANAM-1 to DMOS5 Wafer Fab site																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Jun 30, 2021		Estimated Sample Availability:	Date provided at sample request.																			
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
This change notification is to announce the transfer of select devices from ANAM-1 to the DMOS5 Wafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been built to cover the notification period of this change notification.																							
<table border="1"> <thead> <tr> <th colspan="3">Current (Discontinued)</th> <th colspan="3">New (Transfer to Location)</th> </tr> <tr> <th>Current Fab Site</th> <th>Fab Process</th> <th>Wafer Diameter</th> <th>New Fab Site</th> <th>Fab Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>ANAM-1</td> <td>C10</td> <td>200mm</td> <td>DMOS5</td> <td>C10</td> <td>200mm</td> </tr> </tbody> </table>						Current (Discontinued)			New (Transfer to Location)			Current Fab Site	Fab Process	Wafer Diameter	New Fab Site	Fab Process	Wafer Diameter	ANAM-1	C10	200mm	DMOS5	C10	200mm
Current (Discontinued)			New (Transfer to Location)																				
Current Fab Site	Fab Process	Wafer Diameter	New Fab Site	Fab Process	Wafer Diameter																		
ANAM-1	C10	200mm	DMOS5	C10	200mm																		
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Discontinued Fab support from ANAM-1																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
Current																							
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																				
ANAM-1	ANM	KOR	Bucheon-si																				
New Fab Site																							
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City																				
DP1DM5	DM5	USA	Dallas																				
Sample product shipping label (not actual product label)																							
  <div style="display: flex; flex-direction: row-reverse;"> <div style="text-align: right;"> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033517 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS </div> </div>																							
Product Affected Group:																							
CDCLVD1204RGTR	CDCLVD1204RGTT	CDCLVD2108RGZR	CDCLVD2108RGZT																				

Qualification Report

Approve Date 23-March-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CDCLVD2108RGZ	Qual Device: CDCLVD1204RGT	QBS Reference: TLK2500IRCP	QBS Reference: TLK2201BIRCP
AC	Autoclave 121C, 2atm	96 Hours	-	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	-	-	1/3/0
ED	Electrical Characterization	Per Data Sheet Parameters	-	-	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
HBM	ESD - HBM	4000 V	-	-	-	1/3/0
HTOL	Life Test, 155C	240 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/135/0	3/135/0
LU	Latch-up	(Per JESD78)	-	-	-	1/6/0
T/C	Temp Cycle -65C/150C	500 Cycles	-	-	-	3/231/0
WBP	Bond Pull	Wires	Pass	Pass	-	-
WPS	Ball Bond Shear	Wires	Pass	Pass	-	-

- Qual Devices qualified at LEVEL3-260C: CDCLVD2108RGZ

- Qual Devices qualified at LEVEL2-260C: CDCLVD1204RGT

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI

intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.